

CLAIMS

1. A substrate polishing apparatus comprising:

a polishing portion that polishes a substrate in a polishing chamber;

a gas supply port that supplies gas to the polishing chamber;

a gas discharge port that discharges the gas from inside the polishing chamber; and

a spray nozzle that is provided on an inner side wall surface of the polishing chamber and sprays a cleaning liquid in a mist into the polishing chamber,

wherein the gas supply port is provided on the inner side wall surface of the polishing chamber and is arranged at a position offset sideward from the center of the inner side wall surface,

wherein the spray nozzle is provided on the inner side wall surface of the polishing chamber, and

wherein the gas discharge port is provided on a horizontal floor of the polishing chamber.

2. The substrate polishing apparatus according to claim 1, wherein

a direction of the spray nozzle is set to spray the cleaning liquid toward a space at the center of the polishing chamber from the inner side wall surface thereof.

3. The substrate polishing apparatus according to claim 2, wherein a plurality of the gas supply ports are each

provided at different positions in an upper part of the polishing chamber.

4. The substrate polishing apparatus according to claim 2, wherein

the gas supply port is provided in an upper part of the polishing chamber, and

the spray nozzle is arranged in the vicinity of the gas supply port.

5. The substrate polishing apparatus according to claim 2, wherein

the gas discharge port is provided in the vicinity of the polishing portion in a lower part of the polishing chamber, and

the spray nozzle is arranged in the vicinity of the gas discharge port.

6. The substrate polishing apparatus according to claim 1, wherein the direction of the spray nozzle is set in a direction opposite to the flow of the gas supplied from the gas supply port.

7. The substrate polishing apparatus according to claim 1, wherein the direction of the spray nozzle is set in the same direction as that of the flow of the gas supplied from the gas supply port.

8. The substrate polishing apparatus according to claim 1,
further comprising

a hand-held cleaning tool for cleaning the inside of the
polishing chamber, and

a sealed glove for operating the hand-held cleaning tool
from outside the polishing chamber.

9. The substrate polishing apparatus according to claim 8,
further comprising a fixing member for fixing the sealed glove to
the inner side wall surface of the polishing chamber.